

General Description

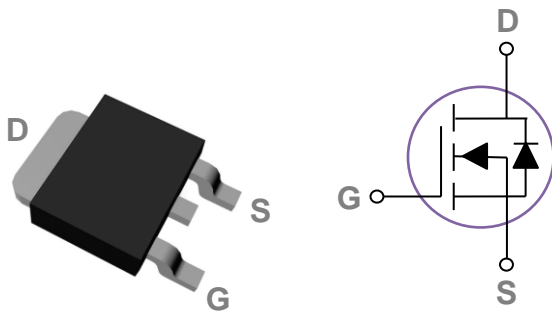
These N-Channel enhancement mode power field effect transistors are using super junction MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
700V	1.6Ω	5A

Features

- 700V,5A, RDS(ON) =1.6Ω @VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

TO252 Pin Configuration



Applications

- PFC Power Supply Stages
- Motor Control
- DC-DC Converters
- Adapter

Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	700	V
V _{GS}	Gate-Source Voltage	±30	V
I _D	Drain Current – Continuous (T _C =25°C)	5	A
	Drain Current – Continuous (T _C =100°C)	3.2	A
I _{DM}	Drain Current – Pulsed ¹	20	A
EAS	Single Pulse Avalanche Energy	159	mJ
P _D	Power Dissipation (T _C =25°C)	33	W
	Power Dissipation – Derate above 25°C	0.26	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	3.8	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	700	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=700V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=560V, V_{GS}=0V, T_J=100^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	± 100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=1A$	---	1.3	1.6	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	2	3	4	V

Dynamic and switching Characteristics²

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge	$V_{DS}=560V, V_{GS}=10V, I_D=5A$	---	9	18	nC
Q_{gs}	Gate-Source Charge		---	0.8	3	
Q_{gd}	Gate-Drain Charge		---	5.5	11	
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=350V, V_{GS}=10V, R_G=25\Omega, I_D=5A$	---	10	20	ns
T_r	Rise Time		---	25	50	
$T_{d(off)}$	Turn-Off Delay Time		---	25	50	
T_f	Fall Time		---	30	60	
C_{iss}	Input Capacitance	$V_{DS}=100V, V_{GS}=0V, F=1\text{MHz}$	---	220	440	pF
C_{oss}	Output Capacitance		---	18	36	
C_{rss}	Reverse Transfer Capacitance		---	4	8	
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	18	---	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{DD}=100V, L=79.9\text{mH}, I_{AS}=1A$	40	---	---	mJ

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$	---	---	5	A
I_{SM}	Pulsed Source Current		---	---	10	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=5A, T_J=25^\circ\text{C}$	---	---	1.4	V
t_{rr}	Reverse Recovery Time	$V_R=400V, I_S=3A$	---	230	---	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=100A/\mu\text{s}, T_J=25^\circ\text{C}$	---	1.6	---	μC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. Essentially independent of operating temperature.

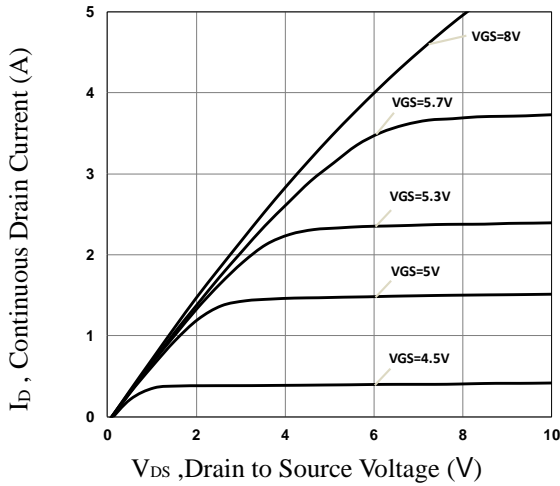


Fig.1 Typical Output Characteristics

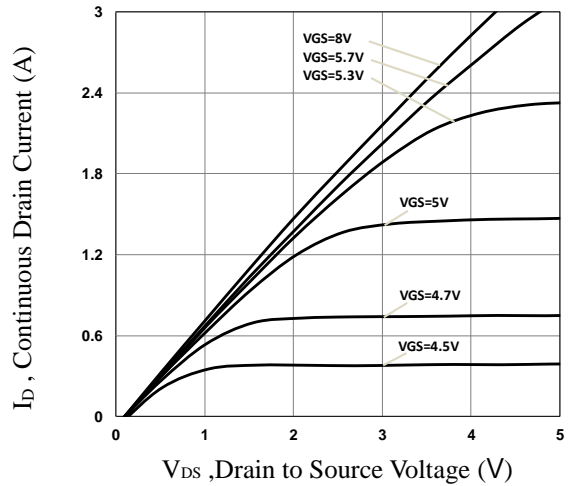


Fig.2 Typical Output Characteristics

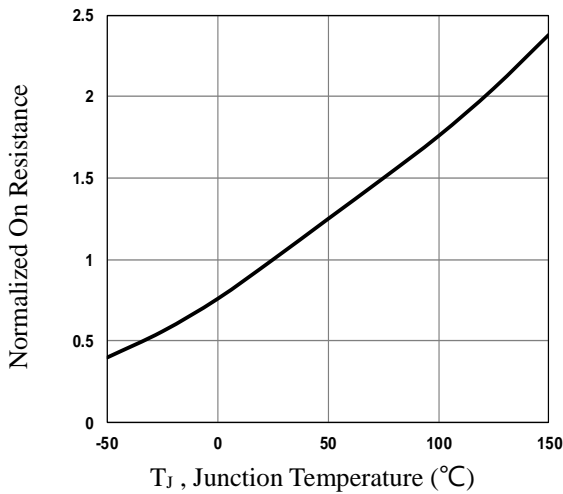


Fig.3 Normalized $R_{DS(on)}$ vs. T_J

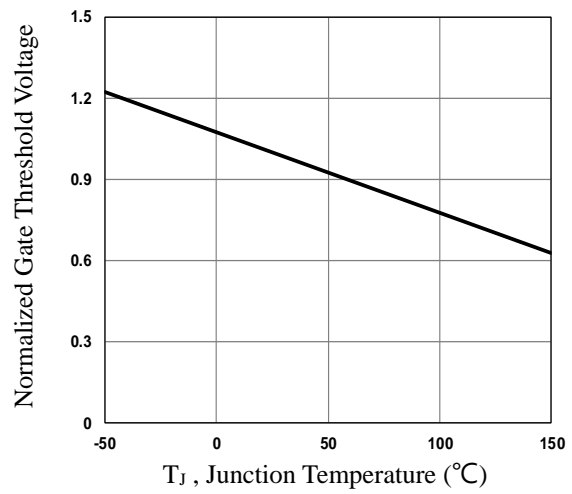


Fig.4 Normalized V_{th} vs. T_J

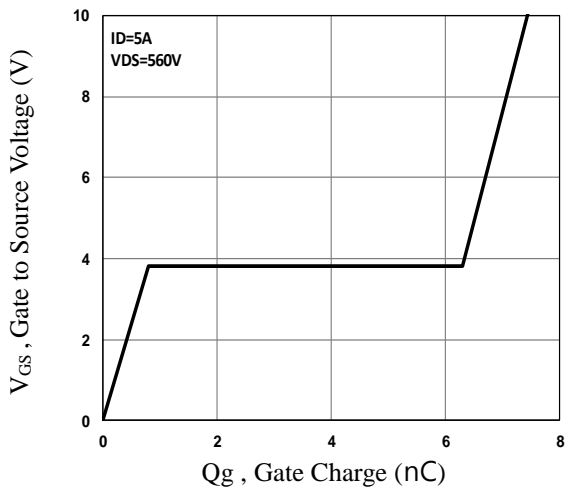


Fig.5 Gate Charge Characteristics

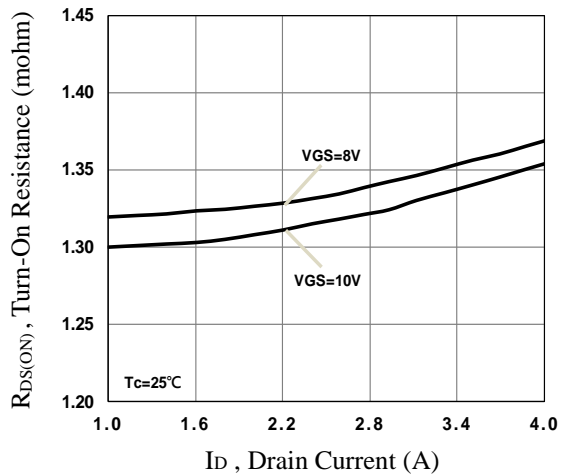


Fig.6 Turn-On Resistance vs. I_D

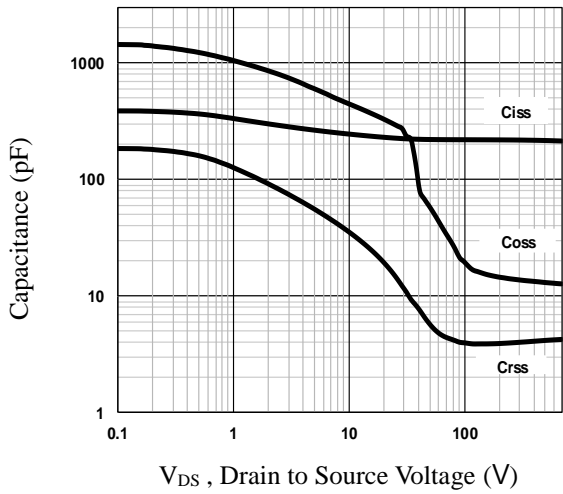


Fig.7 Capacitance Characteristics

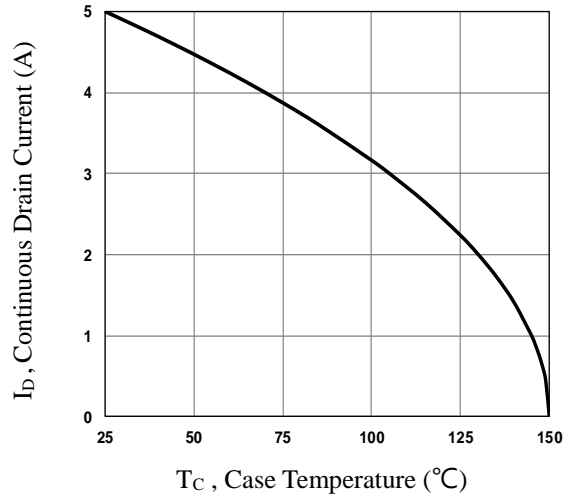


Fig.8 Continuous Drain Current vs. T_c

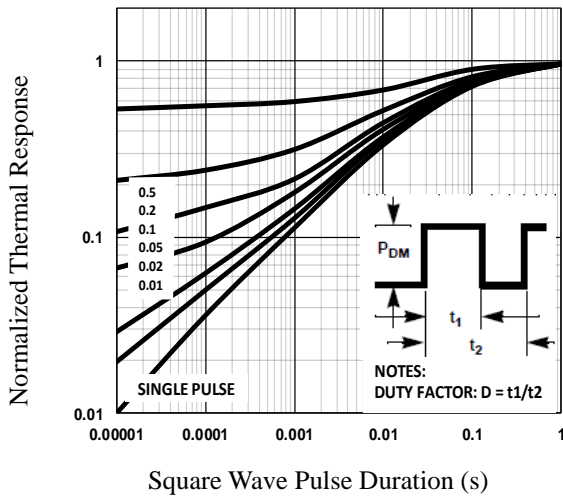


Fig.9 Normalized Transient Impedance

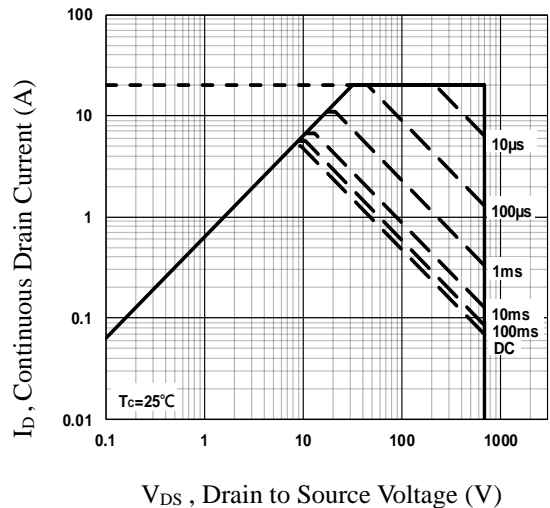


Fig.10 Maximum Safe Operation Area

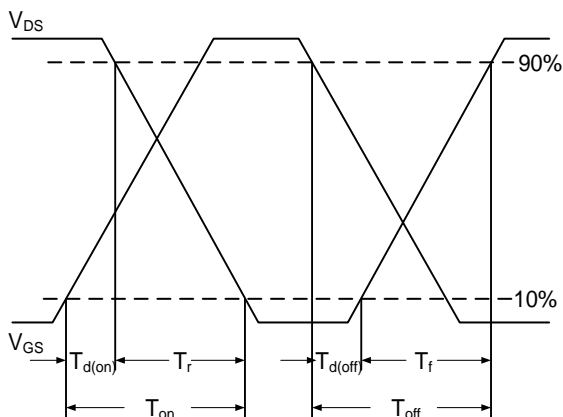


Fig.11 Switching Time Waveform

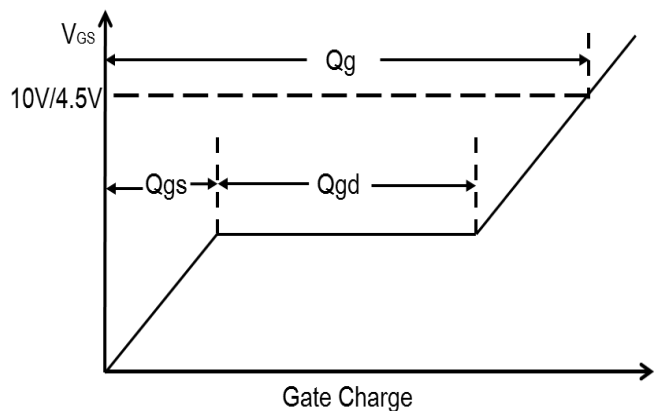
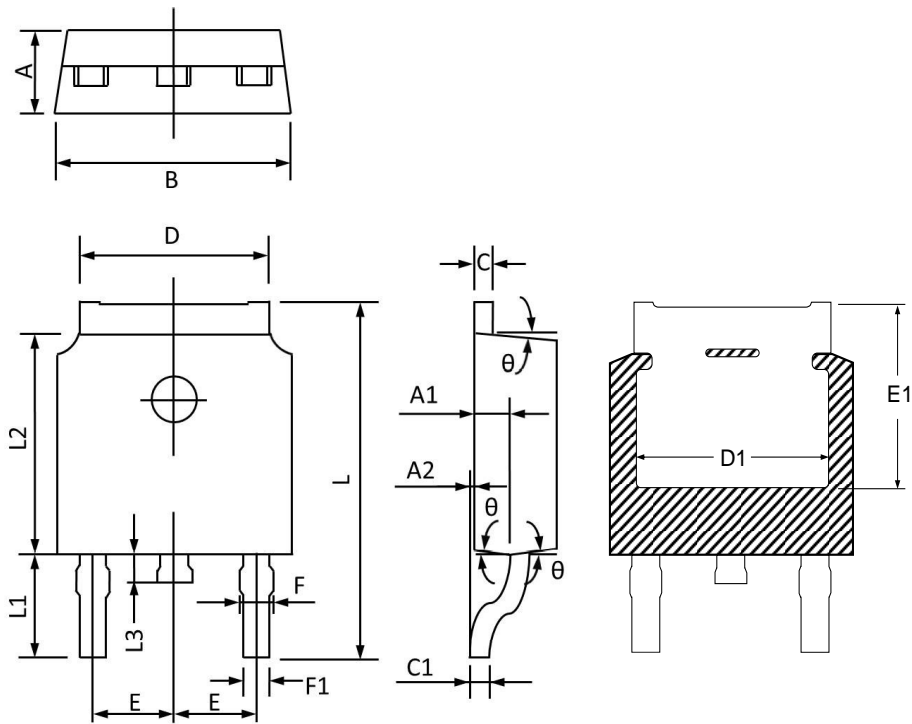


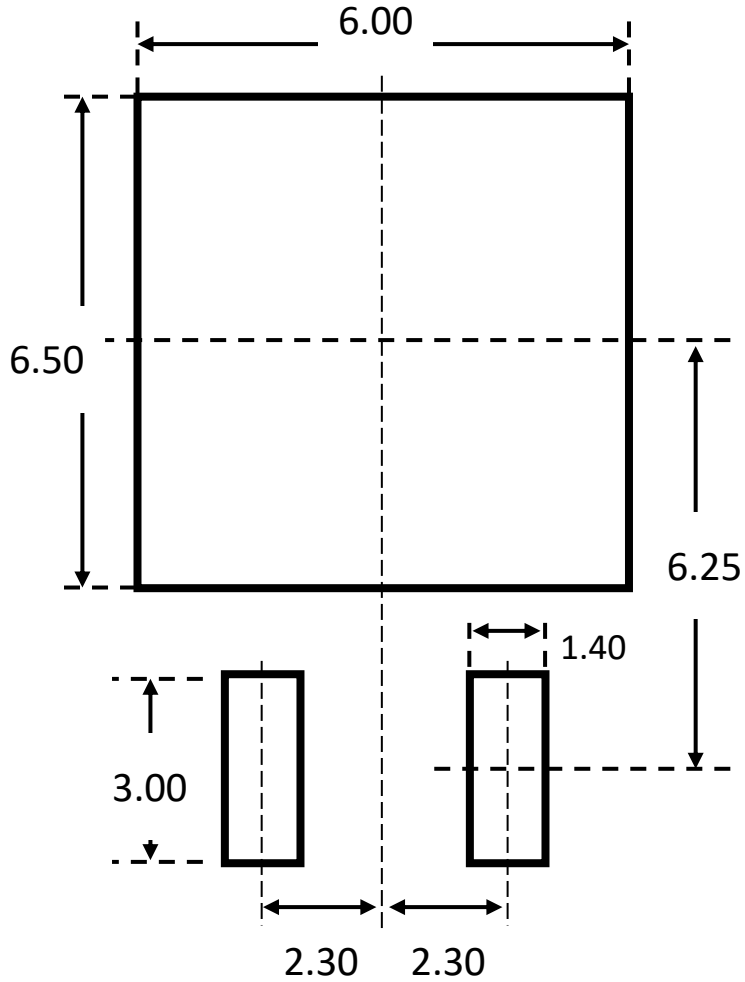
Fig.12 Gate Charge Waveform

TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.450	2.150	0.096	0.085
A1	1.200	0.900	0.047	0.035
A2	0.250	0.000	0.010	0.000
B	6.800	6.300	0.268	0.248
C	0.600	0.350	0.024	0.014
C1	0.600	0.380	0.024	0.015
D	5.500	5.100	0.217	0.201
D1	5.400	4.950	0.212	0.195
E	2.400	2.000	0.094	0.079
E1	5.650	4.950	0.222	0.194
F	1.150	0.600	0.045	0.024
F1	0.900	0.500	0.035	0.020
L	10.400	9.400	0.409	0.370
L1	3.100	2.400	0.122	0.094
L2	6.300	5.300	0.248	0.209
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°

TO252 RECOMMENDED LAND PATTERN



unit : mm